# 2SB1032(K)

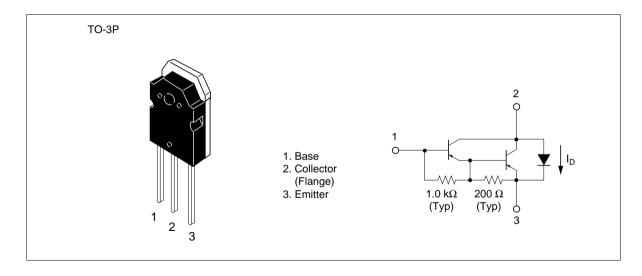
## Silicon PNP Triple Diffused

# **HITACHI**

#### **Application**

Power switching complementary pair with 2SD1436(K)

#### Outline





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## **Absolute Maximum Ratings** (Ta = 25°C)

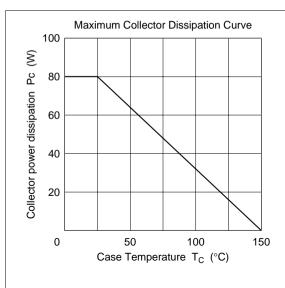
Item	Symbol	Rating	Unit	
Collector to base voltage	$V_{\text{CBO}}$	-120	V	
Collector to emitter voltage	$V_{\text{CEO}}$	-120	V	
Emitter to base voltage	$V_{EBO}$	<b>–</b> 7	V	
Collector current	Ic	-10	А	
Collector peak current	C(peak)	<b>–15</b>	А	
C to E diode forward current	I <sub>D</sub> *1	10	А	
Collector power dissipation	P <sub>c</sub> *1	80	W	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

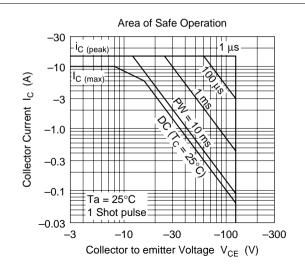
Note: 1. Value at  $T_c = 25^{\circ}C$ 

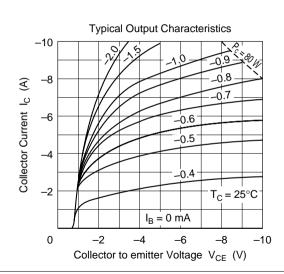
#### **Electrical Characteristics** (Ta = 25°C)

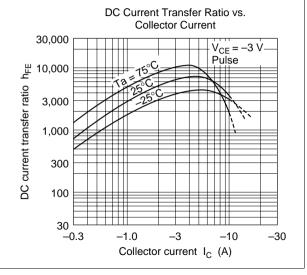
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-120	_	_	V	$I_{c} = -25 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	<b>-7</b>	_	_	V	$I_{\rm E} = -200 \text{ mA}, I_{\rm C} = 0$
Collector cutoff current	I <sub>CBO</sub>	_	_	-100	μΑ	$V_{CB} = -120 \text{ V}, I_{E} = 0$
	I <sub>CEO</sub>	_	_	-10	μΑ	$V_{CE} = -100 \text{ V}, R_{BE} = \infty$
DC current transfer ratio	h <sub>FE</sub>	1000	_	20000		$V_{CE} = -3 \text{ V}, I_{C} = -5 \text{ A}^{*1}$
Collector to emitter saturation	V <sub>CE(sat)1</sub>	_	_	-1.5	V	$I_{\rm C} = -5 \text{ A}, I_{\rm B} = -10 \text{ mA}^{*1}$
voltage	V <sub>CE(sat)2</sub>	_	_	-3.0	V	$I_{\rm C} = -10 \text{ A}, I_{\rm B} = -0.1 \text{ A}^{*1}$
Base to emitter saturation	V <sub>BE(sat)1</sub>	_	_	-2.0	V	$I_{\rm C} = -5 \text{ A}, I_{\rm B} = -10 \text{ mA}^{*1}$
voltage	$V_{BE(sat)2}$	_	_	-3.5	V	$I_{\rm C} = -10 \text{ A}, I_{\rm B} = -0.1 \text{ A}^{*1}$
C to E diode forward voltage	V <sub>D</sub>	_	_	3.0	V	I <sub>D</sub> = 10 A*1
Turn on time	t <sub>on</sub>	_	0.8	_	μs	V <sub>CC</sub> = −30 V,
Turn off time	t <sub>off</sub>	_	4.0	_	μs	$I_{\rm C} = -5 \text{ A}, I_{\rm B1} = -I_{\rm B2} = -10 \text{ mA}$

Note: 1. Pulse test

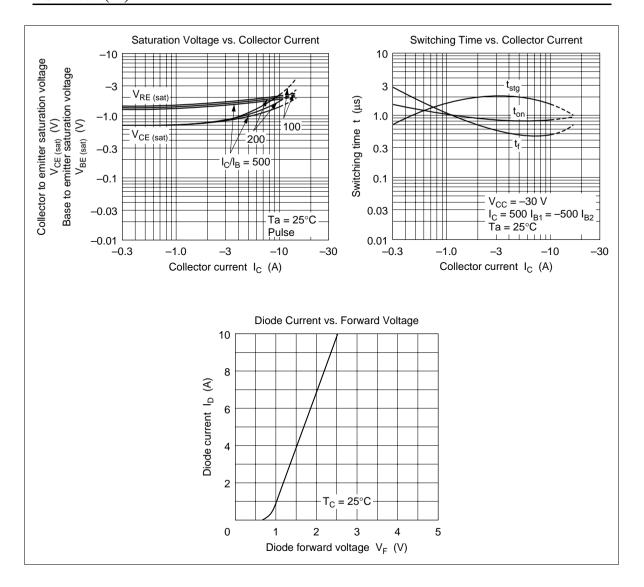




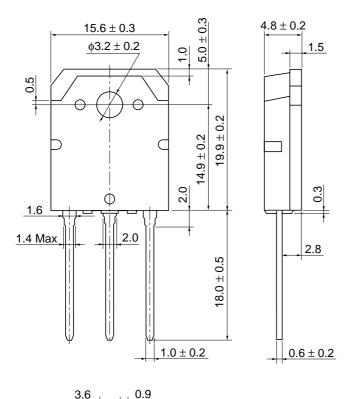


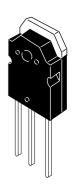


## 2SB1032(K)



Unit: mm





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5.45 ± 0	0.5					5.4	45 ±	0.5

Hitachi Code	TO-3P
JEDEC	
EIAJ	Conforms
Weight (reference value)	5.0 g

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